

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10525996			
<b>Filing Date:</b>	28-Feb-2005			
<b>Title of Invention:</b>	Protective structure of semiconductor wafer, method for protecting semiconductor wafer, multilayer protective sheet used therein, and method for processing semiconductor wafer			
First Named Inventor/Applicant Name:	Hideo Senoo			
<b>Filer:</b>	Kent E. Baldauf/Dianne Kimak			
<b>Attorney Docket Number:</b>	1217-050618			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120